

Fig. 1

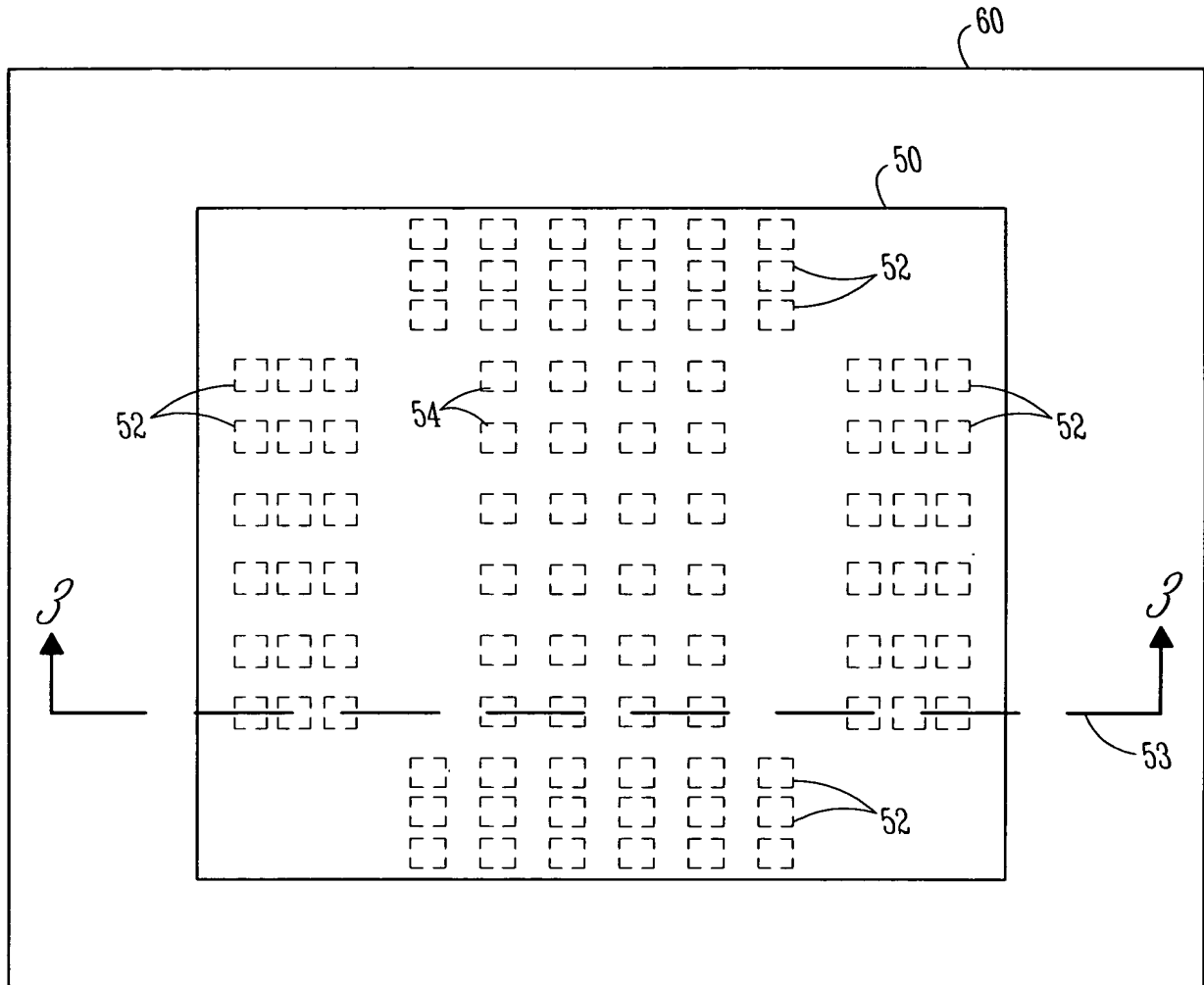


Fig.2 (Prior Art)

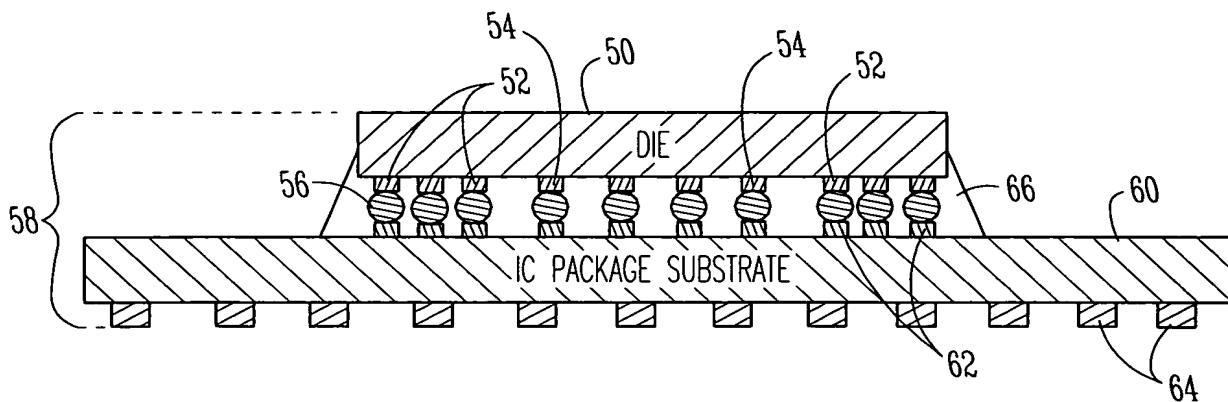


Fig. 3 (Prior Art)

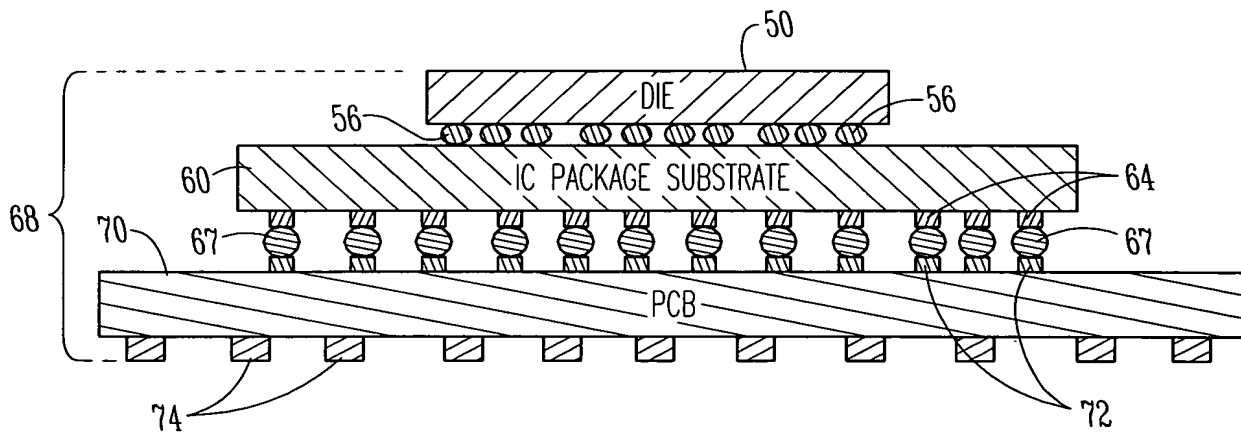


Fig. 4 (Prior Art)



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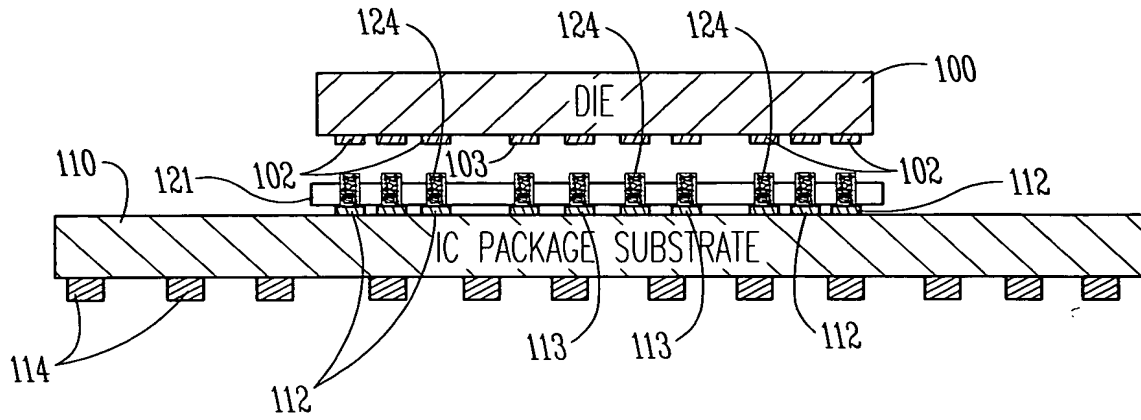


Fig. 5



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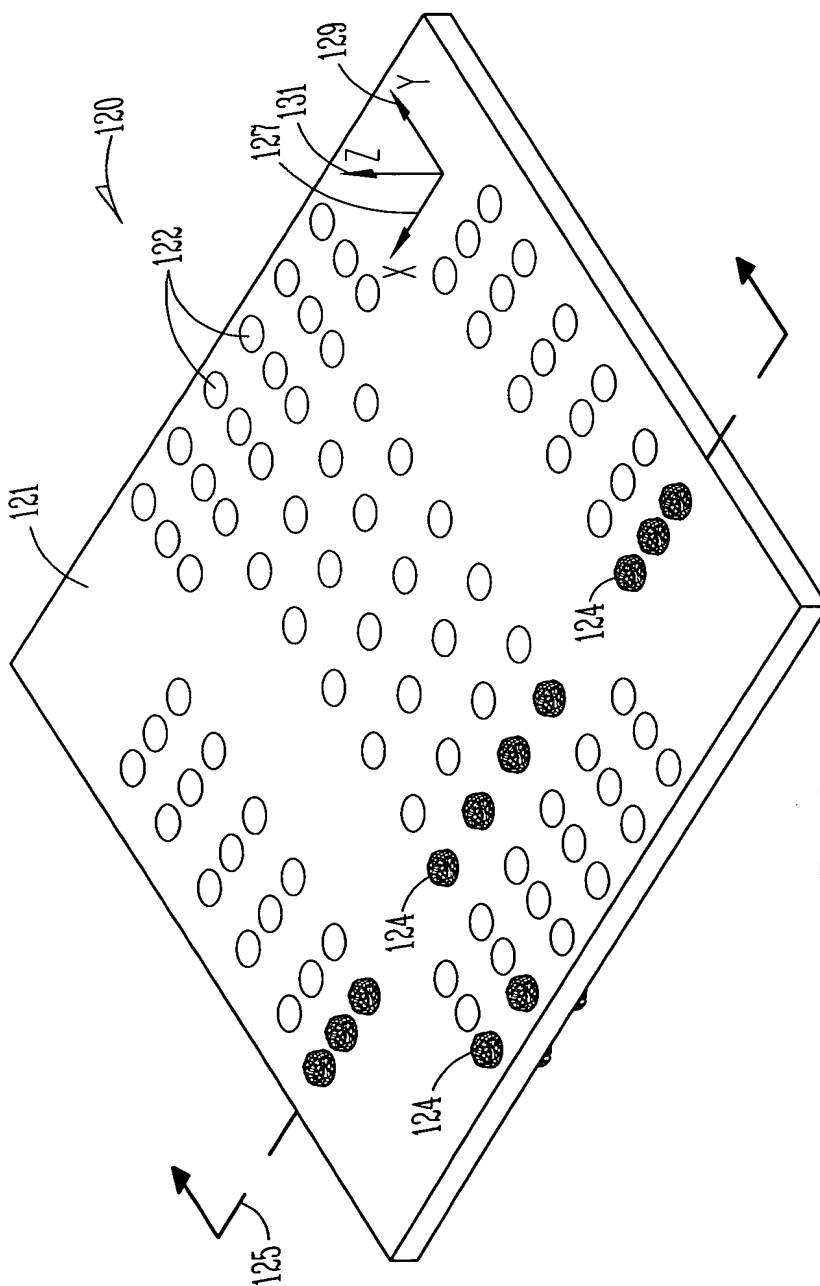


Fig. 6

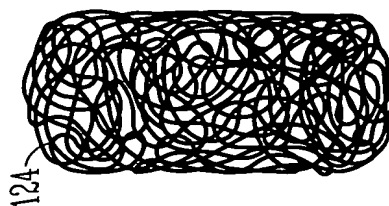
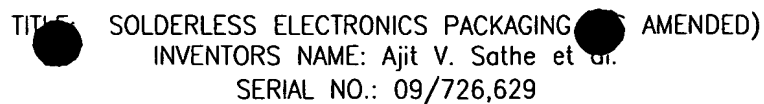


Fig. 7



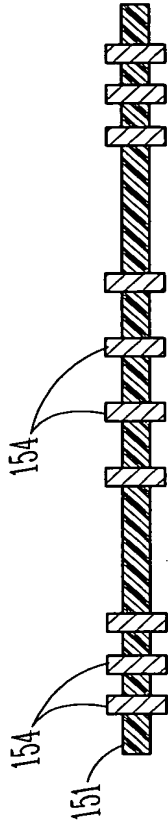


Fig. 10

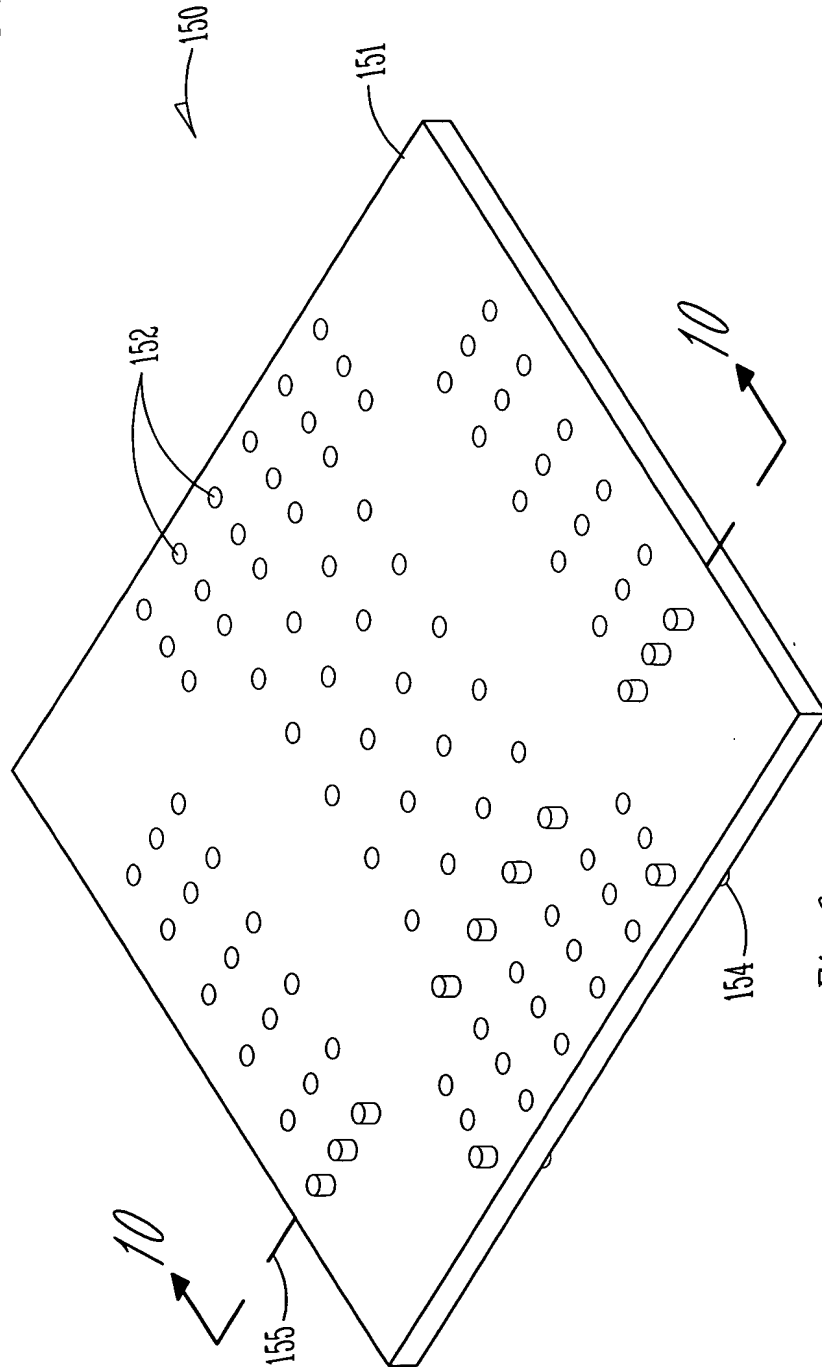


Fig. 9



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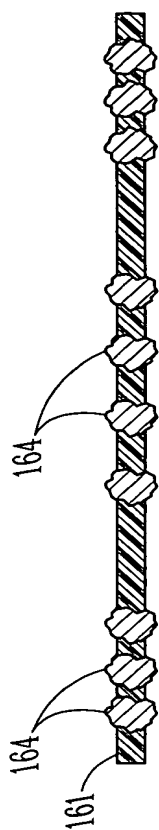


Fig. 12

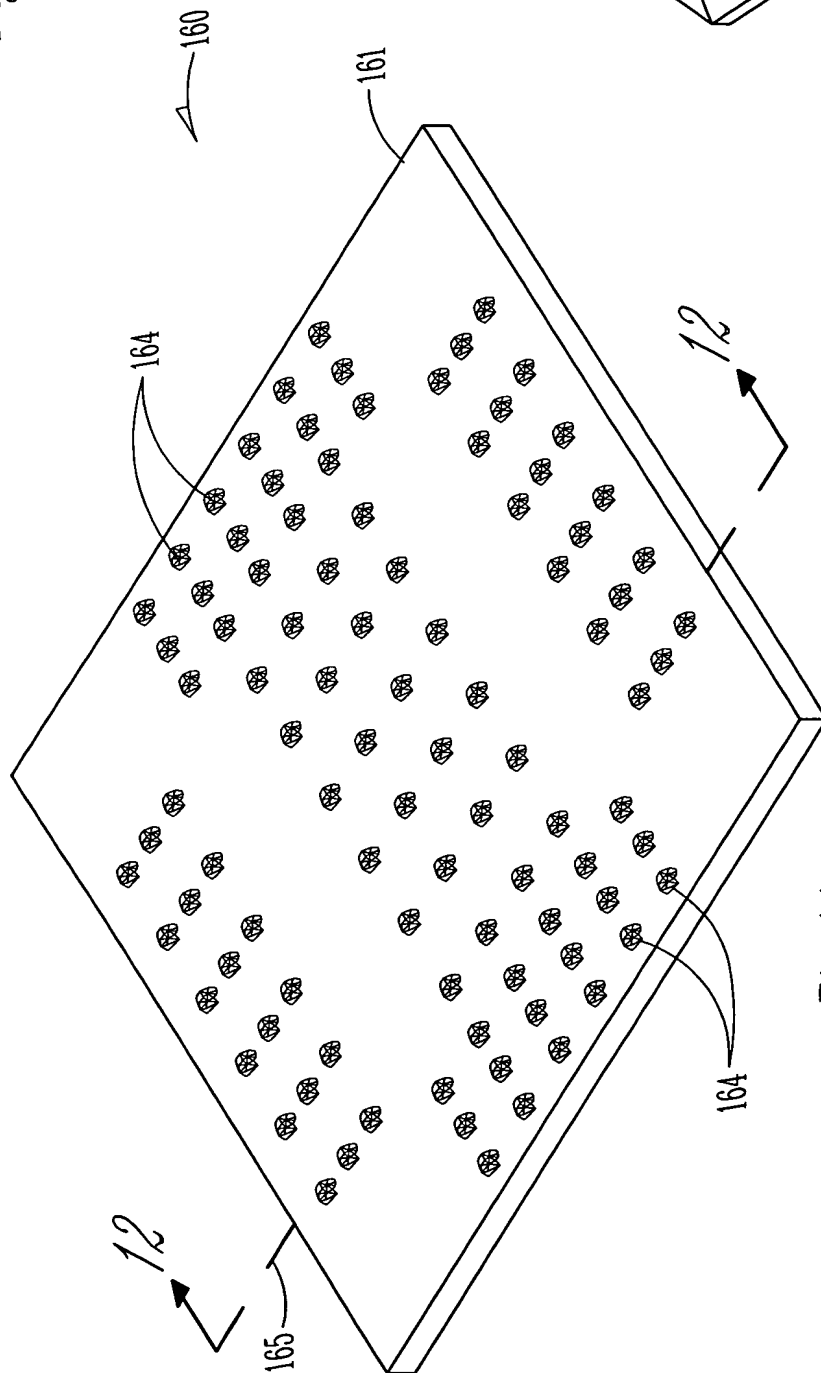


Fig. 11

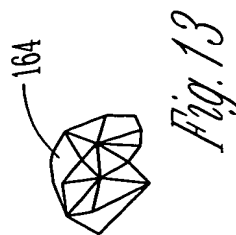


Fig. 13

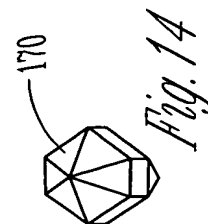


Fig. 14

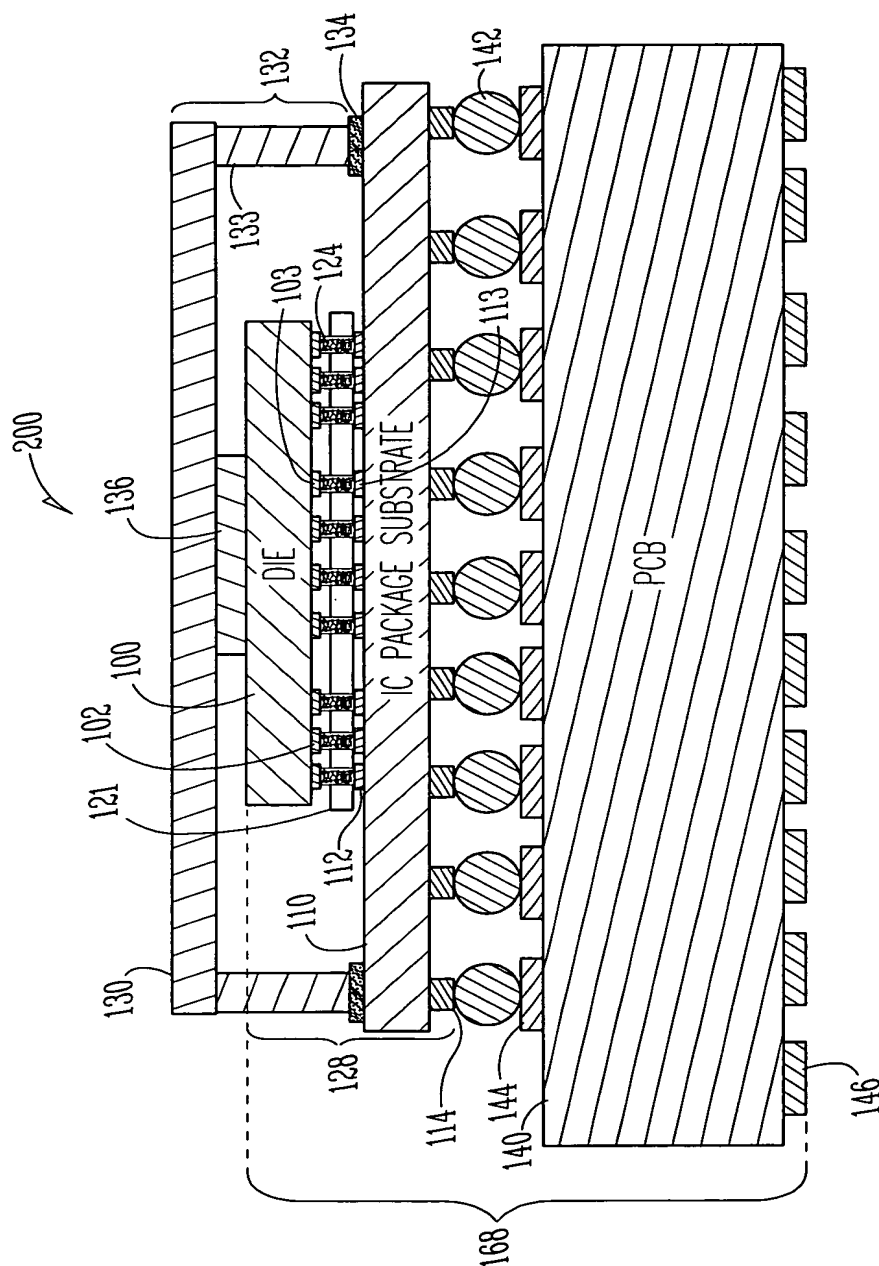
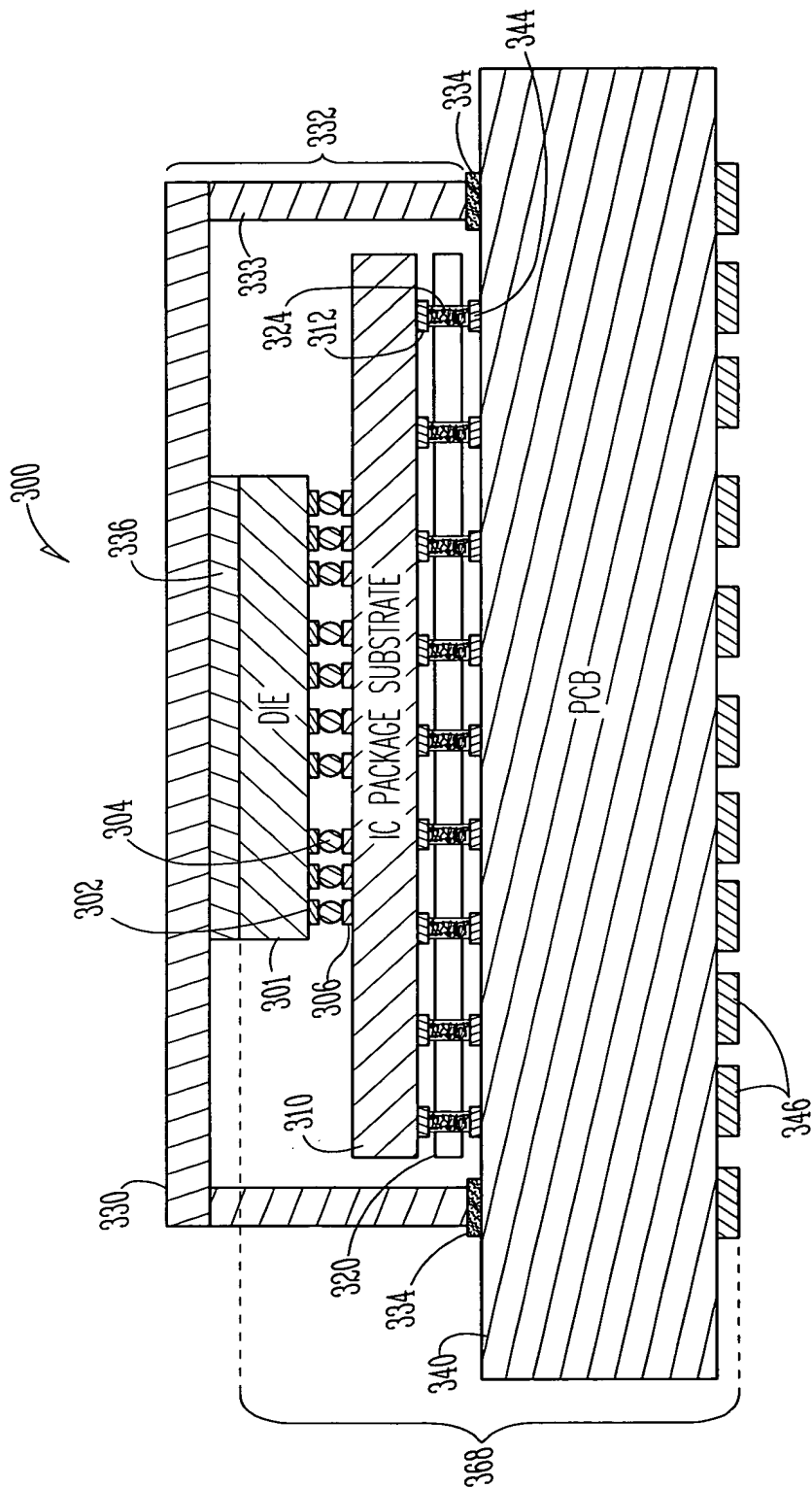


Fig. 15



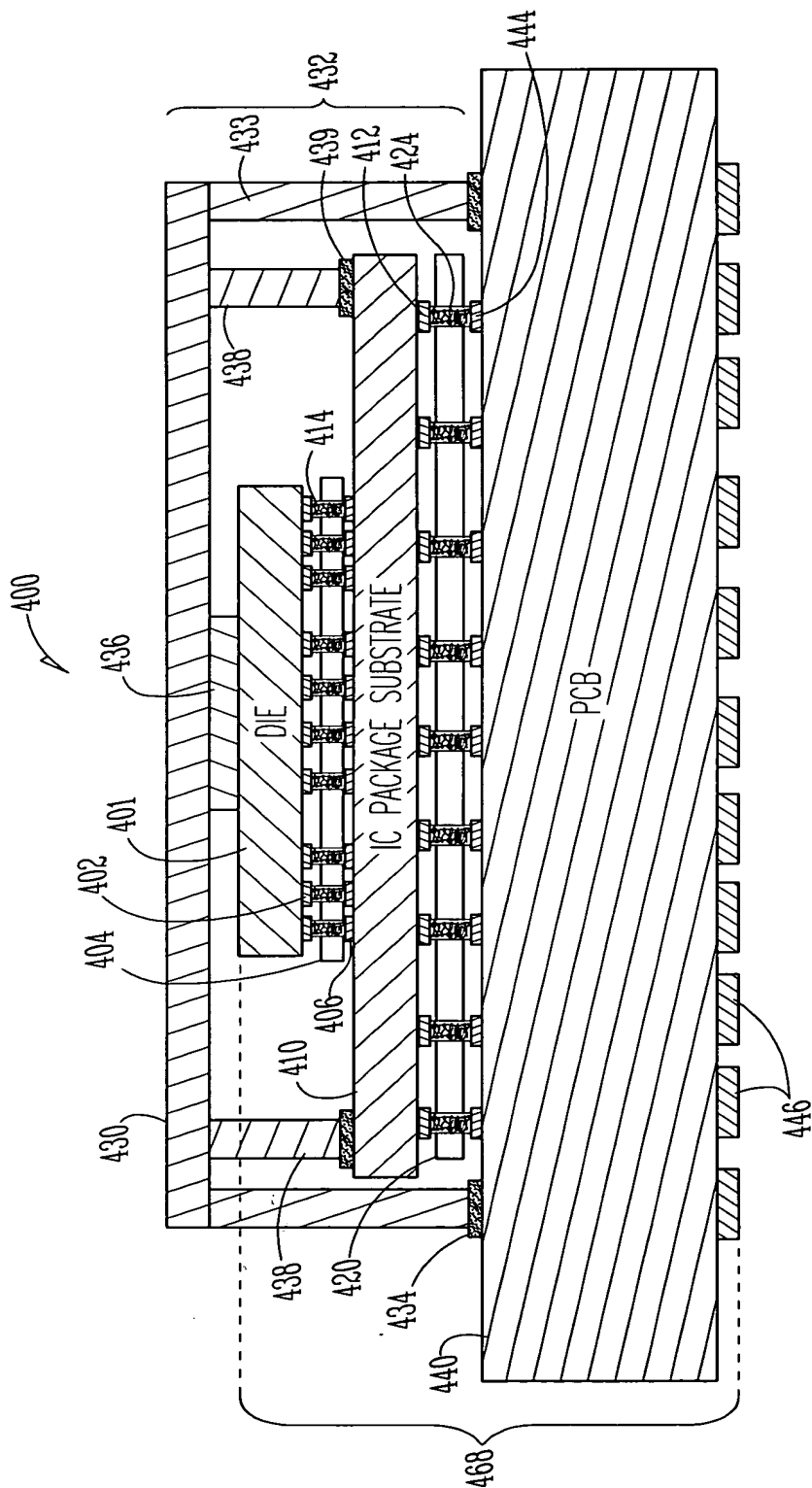


Fig. 17



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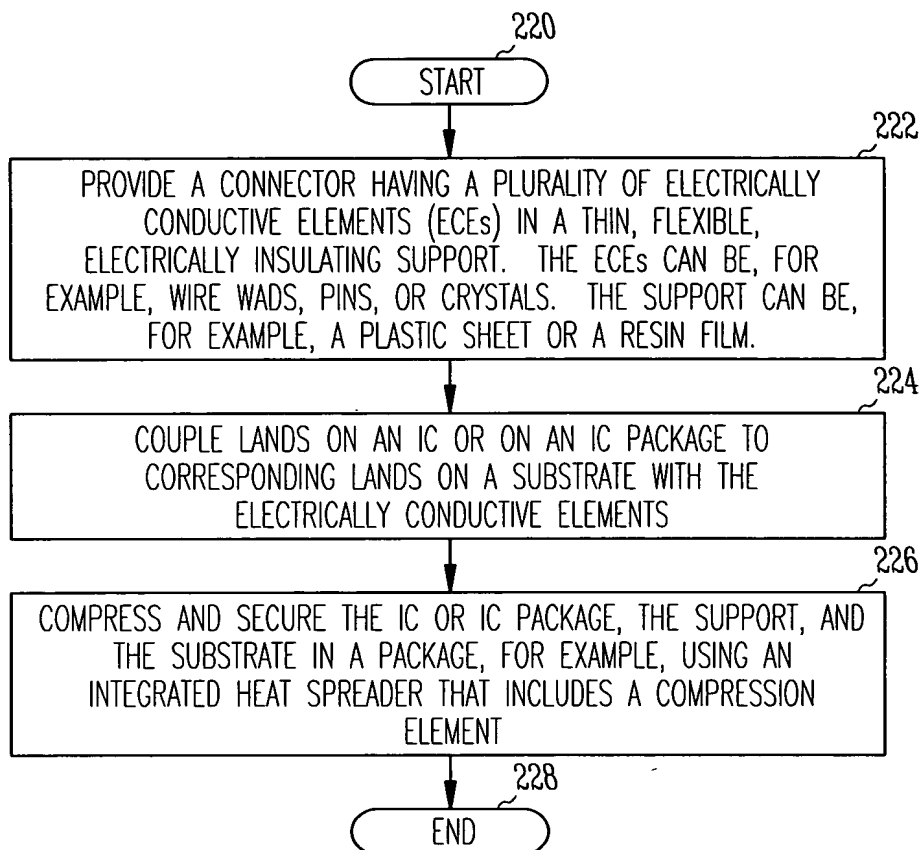


Fig. 18

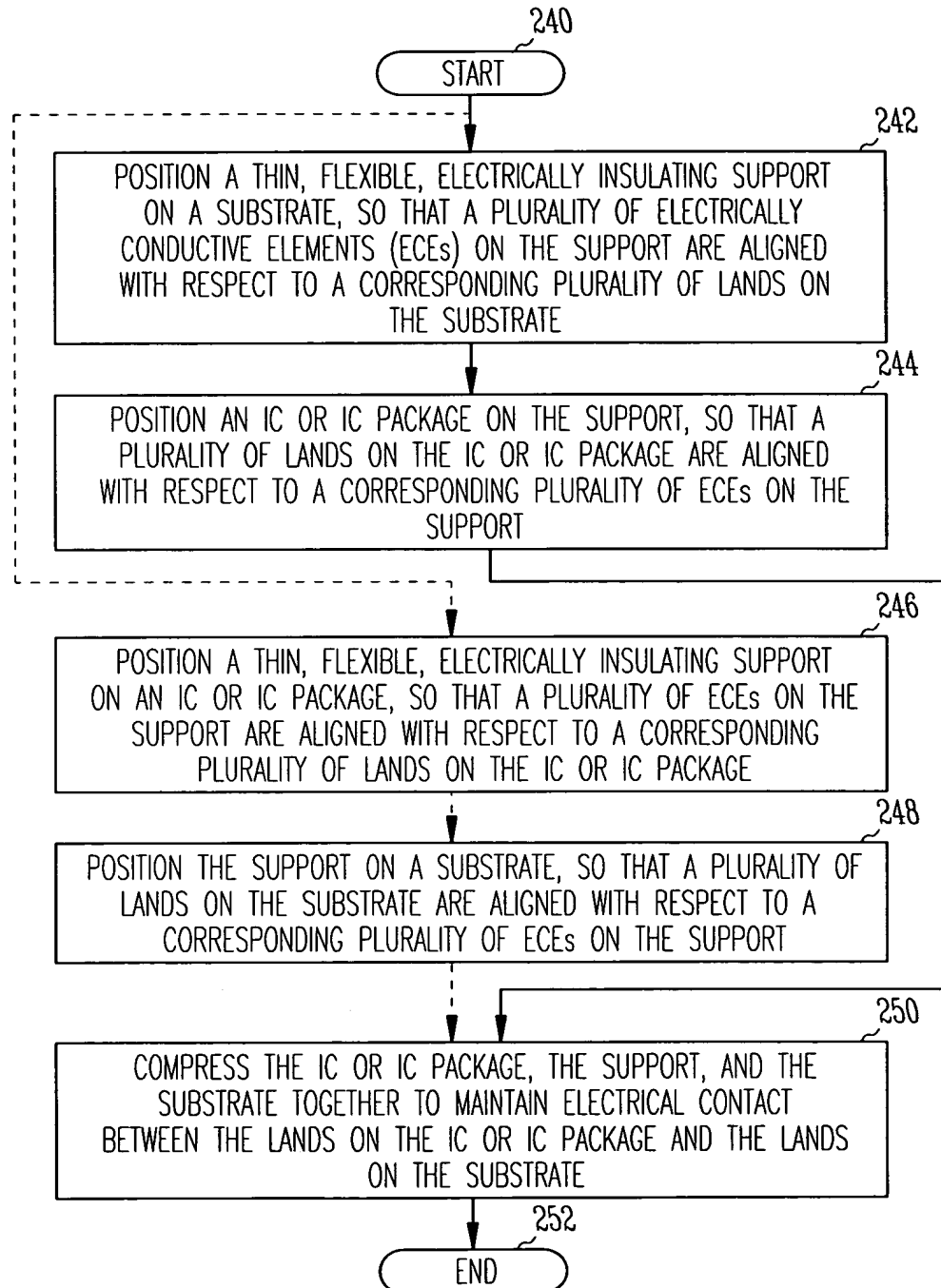


Fig. 19